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# Identification cards — Test methods —

## Part 3:
## Integrated circuit cards with contacts and related interface devices

*Cartes d'identification — Méthodes d'essai —*

*Partie 3: Cartes à circuit(s) intégré(s) à contacts et dispositifs d'interface assimilés*

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# Foreword

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This document was prepared by ISO/IEC JTC 1, *Information technology*, SC 17, *Cards and personal identification*.

This third edition cancels and replaces the second edition (ISO/IEC 10373-3:2010), which has been technically revised. It also incorporates the Technical Corrigendum ISO/IEC 10373-3:2010/Cor 1:2013.

The main changes compared to the previous edition are as follows:

- editorial clarification of scenario 6 (6.3.6.2.3 in the previous edition) with addition of supported PCB values;
- miscellaneous editorial improvement on e.g. symbols, notes and references.

A list of all the parts in the ISO 10373 series can be found on the ISO website.

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